



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): TAKAHASHI, et al.

Serial No.:

09/414,520 (CPA)

Filed:

October 8, 1999

For:

PLASMA PROCESSING APPARATUS AND A PLASMA

PROCESSING METHOD

Group:

1763

Examiner:

Zervigon, R.

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<u>AMENDMENT</u>

Assistant Commissioner for Patents Washington, D.C. 20231

June 19, 2002

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Sir:

In response to the Office Action of February 19, 2002, please amend the application as follows:

IN THE CLAIMS

Please amend Claims 1 and 6 as follows:

1. (four times amended) In a plasma processing apparatus for etching an electrically insulating film, the plasma processing apparatus having a vacuum processing chamber, a sample table for mounting a sample which is processed in said vacuum processing chamber, and a plasma generation means, wherein a plasma processing is carried out by generating a plasma in response to introduction of a gas